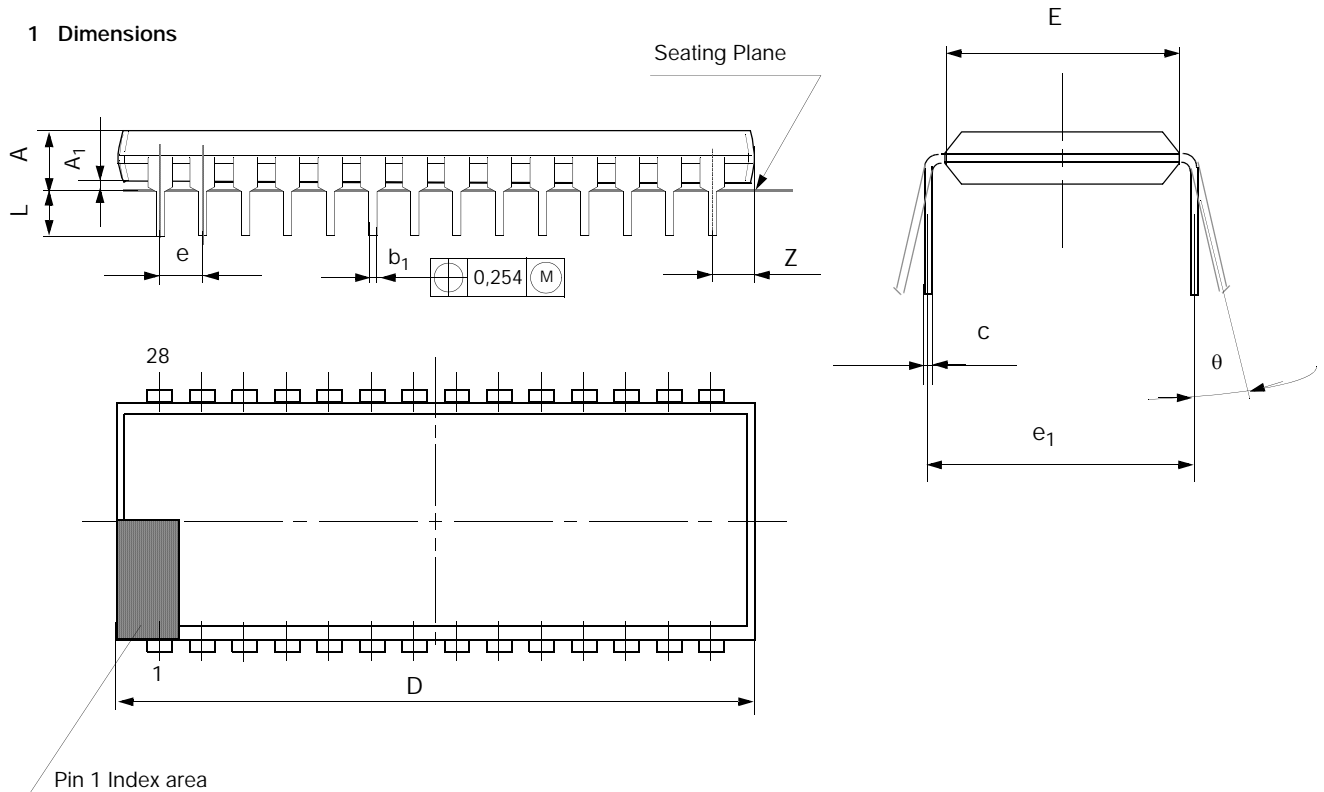
	<b>Package PDIP28</b> (600 mil)	<b>MDS</b> <b>713</b>
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Supersedes  
Edition 11.95

Dimensions in millimetres

Based on IEC 191-2N: Type 051G06

## 1 Dimensions



Dimensions of Sub-Group B1	
$A_{max}$	5,10
$A_{1min}$	0,38
$b_{1min}^{**}$	0,35
$b_{1max}^{**}$	0,59
$c_{min}$	0,20
$c_{max}$	0,36
$e_{nom}$	2,54
$e_{1nom}$	15,24
$E_{min}^*$	13,60
$E_{max}^*$	14,30
$L_{min}$	2,60
$Z_{max}$	2,54

Dimensions of Sub-Group C1	
$A_{min}$	3,00
$A_{1max}$	1,80
$L_{max}$	5,00
$D_{min}^*$	36,70
$D_{max}^*$	37,50
$\theta_{min}$	0°
$\theta_{max}$	15°

\* without mold-flash

\*\*The lead position tolerance requires slots with a minimum diameter of 0,7mm. The spacing between adjacent slots is 2,54mm.

- 2 Weight**  $\leq 4,0$  g
- 3 Package Body Material** Low Stress Epoxy
- 4 Lead Material** FeNi-Alloy or Cu-Alloy
- 5 Lead Finish** solder plating

Zentrum Mikroelektronik Dresden AG		
Editor: signed Schoder	Date: 27.11.2001	Doc-No. QS-000713-HD-03
Check: signed Marx	Quality signed Lorenz:	